

Chapter 5

Field Effect Transistors

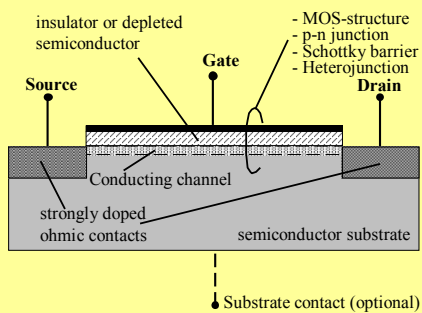
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Contents

- **Principle of operation of FETs:**
 - Basic structure and properties
 - Introduction of various types of FETs (MOSFET, MESFET, HFET, TFT)
- **Basic FET modeling:**
 - Gradual channel approximation
 - Basic FET models: Threshold voltage, charge control models, velocity saturation
 - SPICE implementation and examples

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Principle of FET Operation



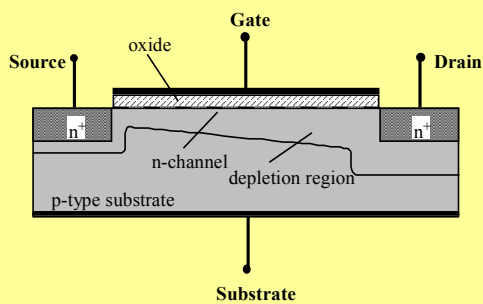
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Principle of FET Operation (Cont.)

- Conducting semiconductor channel between two ohmic contacts – source and drain
- The gate terminal controls the channel current
- The gate structure acts as a two-terminal device:
 - MOS-structure (MOSFET)
 - $p-n$ junction (JFET)
 - Schottky barrier (MESFET)
 - Heterojunction (HFET)
- The gate is a very high-impedance terminal

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Basic MOSFET Operation



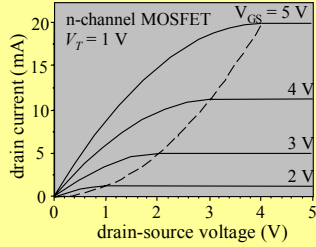
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Basic MOSFET Operation (Cont.)

- The **channel current** is carried by inversion charge at the semiconductor/oxide interface. This charge is controlled by the gate voltage
- The **threshold voltage** V_T defines the onset of strong inversion in the channel
- The channel current saturates at a sufficiently high drain-source voltage. Mechanisms: **Pinch-off** ($V_{SAT} = V_{GS} - V_T$) or **velocity saturation**

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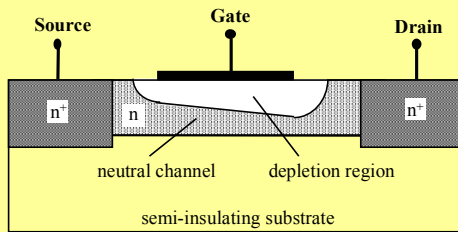
Long-Channel MOSFET Characteristics



- Saturation by pinch-off for *n*-channel MOSFET
- The broken line indicates where the characteristics saturate

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Basic MESFET Operation



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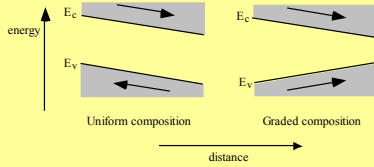
Basic MESFET Operation (Cont.)

- The **channel** is defined by the neutral part of the doped n-type layer. The gate voltage controls the width of the Schottky barrier depletion region
- The **threshold voltage** is defined by full depletion of the channel
- The current saturates because of **saturation** of the electron velocity near drain
- MESFETs are typically made from **GaAs** because of its low effective electron mass and the velocity overshoot effect

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Heterojunctions

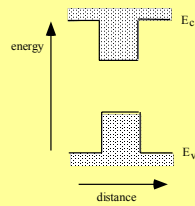
The *conventional p-n diode* uses doping profiles to control current. Using *variation in material composition* gives additional degrees of freedom.



Graded composition: May give a different built-in electric field for electrons and holes

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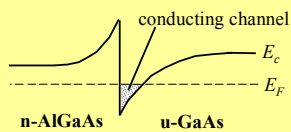
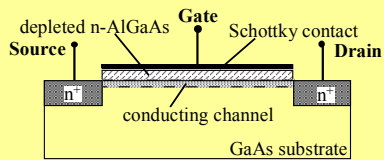
Abrupt Composition



Abrupt composition: Forms energy wells and superlattices

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Basic HFET (HEMT) Operation



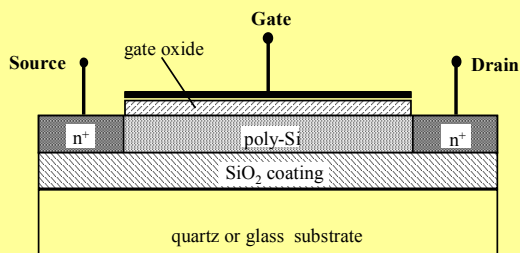
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Basic HFET Operation (Cont.)

- **Material system:** Typically GaAs/AlGaAs
- **Channel:** Defined by electrons populating the quantum well at the GaAs/AlGaAs interface
- **Operation:** Similar to MOSFET
- **Very fast device:** $f_T > 300$ GHz

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Poly-Si TFT Operation

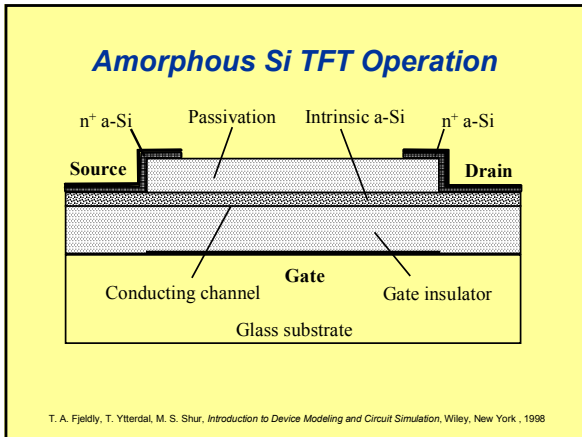


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Poly-Si TFT Operation (Cont.)

- **Channel:** In principle same as for MOSFET
- **Materials:** Polycrystalline Si on glass or quartz substrate
- **Mobility:** 30 – few hundred cm^2/Vs (electron scattering on grain boundaries)
- **Applications:** Large area flat panel displays, printers, scanners

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Amorphous Si TFT Operation (Cont.)

- **Channel:** In principle same as for MOSFET
- **Materials:** Amorphous Si on glass substrate
- **Mobility:** Very low, typically $1 \text{ cm}^2/\text{Vs}$ (large numbers of localized states)
- **Device operation:** Charge injection into channel from n^+ contacts through the intrinsic a-Si layer
- **Applications:** Basically the same as for poly-Si TFTs

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Gradual Channel Approximation

- FETs generally pose a 2D field/transport problem with electric field components parallel and perpendicular to the surface
- GCA: Separate the 2D problem into two coupled 1D equations:
 - Poisson's equation for vertical potential and charge distributions.
 - Charge transport equation for channel current
- GCA valid when $dF_{\parallel}/dx \ll dF_{\perp}/dy$. Typically valid for long-channel MOSFETs and in non-saturated channel regions. Invalid in saturated region.

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Gradual Channel Approximation (Cont.)

Source channel Gate oxide Drain

Non-saturated region Saturated region
GCA valid GCA invalid

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The Meyer MOSFET Model

n-channel depletion region

Use results from the MIS capacitor. Add connections between channel and source and drain.

Total charge per unit area in the semiconductor: $q_s = -c_i [V_{GS} - V_{FB} - 2\phi_b - V(x)]$

Depletion charge per unit area:
 $q_{dep} = -qN_a d_{dep} = -\sqrt{2\epsilon_s q N_a [2\phi_b + V(x)]}$

⇒ Inversion (electronic) charge per unit area:
 $q_i = -qn_s = -c_i [V_{GS} - 2\phi_b - V_{FB} - V(x)] + \sqrt{2\epsilon_s q N_a [2\phi_b + V(x)]}$

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Meyer I-V Characteristics

$$I_d = \frac{W\mu_n c_i}{L} \left\{ \left(V_{GS} - V_{FB} - 2\phi_b - \frac{V_{DS}}{2} \right) V_{DS} - \frac{2\sqrt{2\epsilon_s q N_a}}{3c_i} \left[(V_{DS} + 2\phi_b)^{3/2} - (2\phi_b)^{3/2} \right] \right\}$$

Saturation voltage ($n_s(L) = 0$)

$$V_{SAT} = V_{GS} - 2\phi_b - V_{FB} + \frac{\epsilon_s q N_a}{c_i^2} \left[1 - \sqrt{1 + \frac{2c_i^2 (V_{GS} - V_{FB})}{\epsilon_s q N_a}} \right]$$

Note: $V_{GS} - V_T \equiv V_{GT} = V_{SAT}$ for small N_a

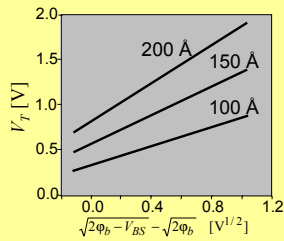
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MOSFET Threshold Voltage

For MIS capacitor: $V_T = V_{FB} + 2\phi_b + \sqrt{4\epsilon_s q N_a \Phi_b} / c_i$

For MOSFET (with source and drain connected) and substrate bias:

$$V_T = V_{FB} + 2\phi_b + \sqrt{2\epsilon_s q N_a (2\phi_b - V_{BS})} / c_i$$



Body plot

Slope: $\gamma = \sqrt{2\epsilon_s q N_a} / c_i$
(Body effect parameter)

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Simple Charge Control I-V Model

Parallel plate capacitor model for inversion charge:
(neglect variation in depletion charge along the channel)

$$q n_s = c_i [V_{GT} - V(x)]$$

I-V characteristics (constant mobility):

$$I_d = W \mu_n q n_s F = W \mu_n c_i (V_{GT} - V) \frac{dV}{dx}$$

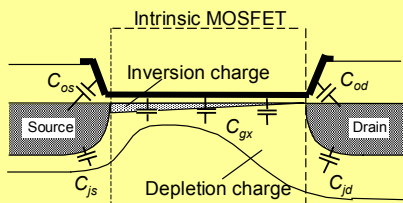
$$\Rightarrow I_d = \frac{W \mu_n c_i}{L} \times \begin{cases} V_{GT} V_{DS} - V_{DS}^2 / 2, & \text{for } V_{DS} \leq V_{SAT} = V_{GT} \\ V_{GT}^2 / 2, & \text{for } V_{DS} > V_{SAT} \end{cases}$$

Transconductance:

$$g_m = \left. \frac{\partial I_d}{\partial V_{GS}} \right|_{V_{DS}} = \frac{W \mu_n c_i}{L} \times \begin{cases} V_{DS}, & \text{for } V_{DS} \leq V_{SAT} \\ V_{GT}, & \text{for } V_{DS} > V_{SAT} \end{cases}$$

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MOSFET Capacitances



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MOSFET Capacitances (Cont.)

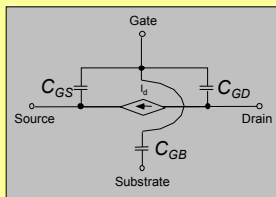
Note: Intrinsic semiconductor charge consists of *inversion charge* and *depletion charge*. In general, these are non-uniformly distributed along the channel.

Capacitance models:

- **Meyer:** Derivatives of intrinsic gate charge with respect to terminal voltages.
- **Ward-Dutton:** Assign inversion charge to source and drain terminals, and depletion charge to substrate terminal.

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Meyer Capacitance Model



$$C_{GS} = \left. \frac{\partial Q_G}{\partial V_{GS}} \right|_{V_{GD}, V_{GB}}$$

$$C_{GD} = \left. \frac{\partial Q_G}{\partial V_{GD}} \right|_{V_{GS}, V_{GB}}$$

$$C_{GB} = \left. \frac{\partial Q_G}{\partial V_{GB}} \right|_{V_{GS}, V_{GD}}$$

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Meyer Capacitance Model (Cont.)

Gate charge in *strong inversion* (inversion charge dominant):

$$Q_G \approx -Q_i = qW \int_0^L n_s dx \approx \frac{2}{3} C_i \frac{(V_{GD} - V_T)^3 - (V_{GS} - V_T)^3}{(V_{GD} - V_T)^2 - (V_{GS} - V_T)^2}$$

Gate charge in *weak inversion* (depletion charge dominant):

$$Q_G \approx -Q_{dep} \approx WL \sqrt{2\epsilon_s q N_a \psi_s} \approx \gamma C_i \left(\sqrt{\gamma^2/4 + V_{GB} - V_{FB}} - \gamma/2 \right)$$

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Meyer Capacitances

Strong inversion:

$$C_{GS} = \frac{2}{3} C_i \left[1 - \left(\frac{V_{SAT} - V_{DS}}{2V_{SAT} - V_{DS}} \right)^2 \right]$$

$$C_{GD} = \frac{2}{3} C_i \left[1 - \left(\frac{V_{SAT}}{2V_{SAT} - V_{DS}} \right)^2 \right]$$

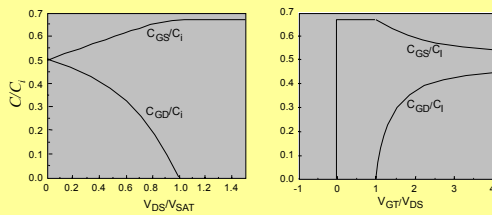
$$C_{GB} = 0$$

Weak inversion:

$$C_{GS} = C_{GD} = 0, \quad C_{GB} = C_i \sqrt{1 + 4(V_{GB} - V_{FB})^2 \gamma^2}$$

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Meyer Capacitances (Cont.)



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Velocity Saturation in MOSFETs

Must be included in short-channel devices

Velocity-field relationships used in MOSFET modeling:

$$v(F) = \frac{\mu F}{\left[1 + (\mu F/v_s)^m \right]^{1/m}}$$

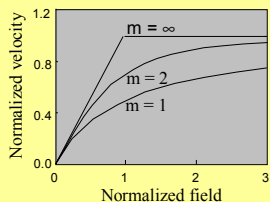
Two-piece v - F model ($m = \infty$):

$$v(F) = \begin{cases} \mu F & \text{for } F < F_s \\ v_s & \text{for } F \geq F_s \end{cases}$$

where $F_s = v_s/\mu$

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Velocity Saturation in MOSFETs II



- $m = 1$ for p -channel MOSFET
- $m = 2$ for n -channel MOSFET
- $m = \infty$ two-piece v - F model

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Simple Velocity Saturation I-V Model

- Use two-piece v - F relationship
- Current saturation occurs when $F(L) = F_s$
- Use simple charge control model below saturation

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Simple Velocity Saturation I-V Model (Cont.)

⇒ I - V characteristics:

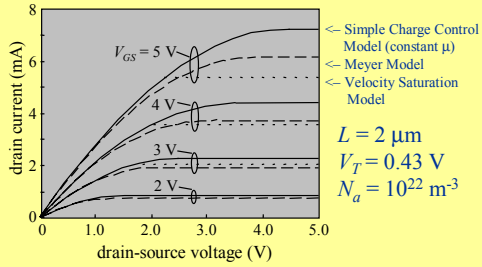
$$I_d = \frac{W \mu_n \epsilon_i}{L} \times \begin{cases} V_{GT} V_{DS} - V_{DS}^2 / 2 & \text{for } V_{DS} \leq V_{SAT} \\ V_L^2 \left[\sqrt{1 + (V_{GT}/V_L)^2} - 1 \right] & \text{for } V_{DS} > V_{SAT} \end{cases}$$

Saturation voltage:

$$V_{SAT} = V_{GT} - V_L \left[\sqrt{1 + \left(\frac{V_{GT}}{V_L} \right)^2} - 1 \right] \quad \text{where } V_L = F_s L$$

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Comparison of Basic MOSFET Models



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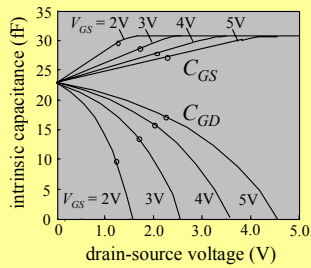
Comparison of Basic MOSFET Models (Cont.)

Conclusion

- SCCM overestimates the saturation current (neglects velocity saturation and variation in depletion charge)
- MM shows effect of including variation in depletion charge
- VSM shows effect of including velocity saturation

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Meyer C-V Model with Velocity Saturation



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Meyer C–V Model with Velocity Saturation

At $V_{DS} = V_{SAT}$:

$$C_{GSs} = \frac{2}{3} C_i \left[1 - \left(\frac{V_{SAT}}{2V_L} \right)^2 \right]$$

$$C_{GDs} = \frac{2}{3} C_i \left[1 - \left(1 - \frac{V_{SAT}}{2V_L} \right)^2 \right]$$

However, $C_{GS} \Rightarrow 2/3 C_i$ and $C_{GD} \Rightarrow 0$ when $V_{DS} > V_{SAT}$, so basic Meyer C–V model is also applicable for short-channel MOSFET.

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MOSFET Level 1 SPICE Model

(Simple Charge Control Model)

Threshold voltage:

$$V_T = V_{TO} + \text{GAMMA} \left(\sqrt{\text{PHI} - V_{BS}} - \sqrt{\text{PHI}} \right)$$

$V_{TO} = V_T(V_{BS} = 0)$ (Threshold voltage at zero substrate bias)

$\text{GAMMA} = \sqrt{2\epsilon_s q N_a} / c_i$ (Body effect parameter)

$\text{PHI} = 2\phi_b = 2V_{th} \ln(N_a/n_i)$ (Surface potential)

(Alternatively, specify $\text{TOX} = d_t$, $\text{NSUB} = N_a$, $\text{UO} = \mu_n$)

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SPICE Level 1 Model (Cont.)

I–V characteristics:

$$I_d = \frac{W \cdot \text{KP} (1 + \text{LAMBDA} \cdot V_{DS})}{L - 2\text{LD}} \times \begin{cases} V_{GT} V_{DS} - V_{DS}^2 / 2, & V_{DS} \leq V_{GT} \\ V_{GT}^2 / 2, & V_{DS} > V_{GT} \\ 0, & V_{GT} < 0 \end{cases}$$

L, W (Gate length and with, specified on the device line)

LD (Lateral diffusion)

KP = $\mu_n c_i$ (Transconductance coefficient)

LAMBDA (Channel length modulation parameter)

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MOSFET Level 2 SPICE Model

(Modified Meyer Model)

Threshold voltage: Same as Level 1, but can define **VTO** in terms of type of gate (**TPG**), substrate doping (**NSUB**), and surface density of states (**NSS**)

Saturation voltage:

$$V_{SAT} = V_{GS} - \text{PHI} - V_{FB} + \frac{\text{GAMMA}^2}{2} \left[1 - \sqrt{1 + \frac{4(V_{GS} - V_{FB})}{\text{GAMMA}^2}} \right]$$

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SPICE Level 2 Model (Cont.)

I-V characteristics (above threshold, below saturation):

$$I_d = \frac{W}{L - 2LD} \frac{KP}{1 - LAMBDA \cdot V_{DS}} \left\{ \left(V_{GS} - V_{FB} - \text{PHI} - \frac{V_{DS}}{2} \right) V_{DS} - \frac{2}{3} \text{GAMMA} \left[(V_{DS} - V_{BS} + \text{PHI})^{3/2} - (-V_{BS} + \text{PHI})^{3/2} \right] \right\}$$

TPG determines V_{FB} . **LAMBDA** can be modeled in terms of **NSUB**.

Additional modeling features: Field (bias) dependent mobility (**UCRIT**, **UTRA**, **UEXP**), velocity saturation (**VMAX**), Subthreshold current (**NFS**)

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MOSFET Level 3 SPICE Model

(Modified Velocity Saturation Model)

I-V characteristics (above threshold, below saturation):

$$I_d = \frac{W}{L - 2LD} KP \left[V_{GT} V_{DS} - \frac{1 + F_B}{2} V_{DS}^2 \right]$$

F_B accounts for short and narrow channel effects, enters into V_T and V_{SAT} . V_T also includes effects of static feedback from drain to channel (**ETA**).

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SPICE Level 3 Model (Cont.)

Saturation voltage:

$$V_{SAT} = \frac{V_{GT}}{1 + F_B} + \frac{V_{MAX}(L - 2LD)}{U_0} - \sqrt{\left(\frac{V_{GT}}{1 + F_B}\right)^2 + \left(\frac{V_{MAX}(L - 2LD)}{U_0}\right)^2}$$

Mobility model: $\mu = \frac{U_0}{1 + \text{THETA} \cdot V_{GT}}$

U0 : Mobility at threshold

THETA : Parameter for dependence on V_{GT}

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Basic MOSFET SPICE Models: Conclusion

- **Level 1:** Simple charge control model – a long channel model, only good for rough estimates. Uses Meyer’s capacitance model. Does not include the subthreshold regime.
- **Level 2:** Modified Meyer model. Includes velocity saturation. Uses Meyer’s capacitance model. This model is quite complex (includes many semi-empirical corrections to describe short-channel effects), and may sometimes have difficulties with convergence.

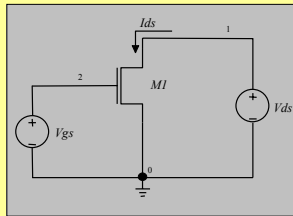
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Basic MOSFET SPICE Models: Conclusion (Cont.)

- **Level 3:** Modified velocity saturation model. Also quite complex, but more efficient than Level 2. Short channel effects are introduced through the correction factor F_B (in the $I-V$ characteristics and in V_T) and through velocity saturation. Contains both the Meyer and the Ward-Dutton capacitance models.

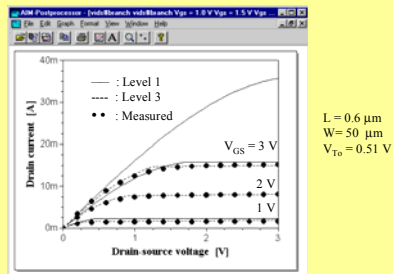
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Example: MOSFET I-V Characteristics



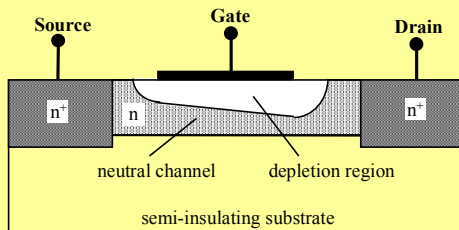
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Short-Channel MOSFET Characteristics



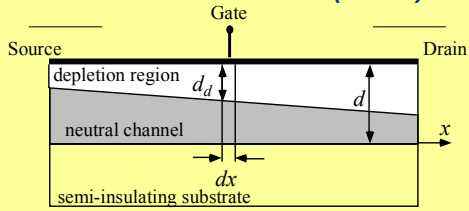
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Basic MESFET Model



T. A. Fjeldly, T. Ytterdal, M. S. Shur, *Introduction to Device Modeling and Circuit Simulation*, Wiley, New York, 1998

Basic MESFET Model (Cont.)



Use results from the Schottky (metal-semiconductor) diode.
Depletion width (Gradual Channel Approximation):

$$d_d(x) = \sqrt{\frac{2\epsilon_s}{qN_d} [V_{bi} - V_{GS} + V(x)]}$$

T. A. Fjeldly, T. Ytterdal, M. S. Shur, *Introduction to Device Modeling and Circuit Simulation*, Wiley, New York, 1998

Basic MESFET Model (Cont.)

Threshold voltage:

$$V_T = V_{bi} - V_{po}$$

Pinch-off voltage:

$$V_{po} = \frac{qN_d d^2}{2\epsilon_s}$$

T. A. Fjeldly, T. Ytterdal, M. S. Shur, *Introduction to Device Modeling and Circuit Simulation*, Wiley, New York, 1998

The Shockley Model

Assume a constant mobility

I-V characteristics ($g_o = qN_d\mu_n Wd/L$):

$$I_d = qN_d W [d - d_d(x)] \mu_n \frac{dV}{dx}$$

$$\Rightarrow I_d = g_o \left\{ V_{DS} - \frac{2}{3V_{po}} \left[(V_{DS} + V_{bi} - V_{GS})^{3/2} - (V_{bi} - V_{GS})^{3/2} \right] \right\}$$

Pinch-off condition:

$$d_d(L) = d$$

Saturation voltage (Pinch-off):

$$V_{SAT} = V_{GS} - V_T = V_{GT}$$

T. A. Fjeldly, T. Ytterdal, M. S. Shur, *Introduction to Device Modeling and Circuit Simulation*, Wiley, New York, 1998

MESFET C-V Model

Because of the similarity between the MESFET Shockley model and the simple MOSFET models, a Meyer-type capacitance model may be used.

Total gate charge ($V_{DS} = 0$):

$$|Q_{G0}| = qN_dWLd_d = qN_dWLd\sqrt{1 - V_{GT}/V_{po}}$$

Corresponding gate-channel capacitance

$$(C_o = \epsilon_s WL/d):$$

$$C_{ch} = \frac{\partial Q_{G0}}{\partial V_{GT}} \Big|_{V_{DS}} = \frac{C_o}{\sqrt{1 - V_{GT}/V_{po}}}$$

T. A. Fjeldly, T. Ytterdal, M. S. Shur, *Introduction to Device Modeling and Circuit Simulation*, Wiley, New York, 1998

MESFET C-V Model (Cont.)

"Meyer" capacitances:

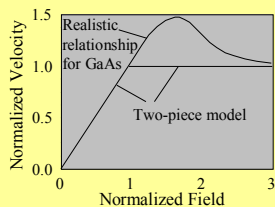
$$C_{GS} = \frac{2}{3} C_{ch} \left[1 - \left(\frac{V_{SAT} - V_{DS}}{2V_{SAT} - V_{DS}} \right)^2 \right]$$

$$C_{GD} = \frac{2}{3} C_{ch} \left[1 - \left(\frac{V_{SAT}}{2V_{SAT} - V_{DS}} \right)^2 \right]$$

In saturation: $C_{GS} = \frac{2}{3} C_{ch}, C_{GD} = 0$

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MESFET Velocity Saturation Model



Two-piece linear v - F model:

$$v(F) = \begin{cases} \mu F, & \text{for } F < F_s \equiv v_s/\mu \\ v_s, & \text{for } F \geq F_s \end{cases}$$

Below saturation – same as for Shockley model

Saturation (approximately):

$$V_{SAT} \approx \left(\frac{1}{V_L} + \frac{1}{V_{GT}} \right)^{-1}$$

T. A. Fjeldly, T. Ytterdal, M. S. Shur, *Introduction to Device Modeling and Circuit Simulation*, Wiley, New York, 1998

Additional MESFET Models

Square-law model: $I_{sat} = \beta V_{GT}^2$

Curtice model (1980): $I_d = I_{sat}(1 + \lambda V_{DS}) \tanh(\alpha V_{DS})$

Statz model (1987): $I_{sat} = \frac{\beta V_{GT}^2}{1 + \alpha V_{GT}}$

Shur (1987): $\beta = \frac{2\epsilon_s v_s W}{d(V_{po} + 3V_L)}$

T. A. Fjeldly, T. Ytterdal, M. S. Shur, *Introduction to Device Modeling and Circuit Simulation*, Wiley, New York, 1998

Basic SPICE MESFET Model

The Statz model – Level 1 in AIM-Spice, Level 2 in PSpice

Linear regime ($V_{DS} < 3/\text{ALPHA}$):

$$I_d = (1 + \text{LAMBDA} \cdot V_{DS}) \frac{\text{BETA} \cdot V_{GT}^2}{1 + \text{B} \cdot V_{GT}} \left[1 - \left(1 - \frac{\text{ALPHA} \cdot V_{DS}}{3} \right)^3 \right]$$

Saturation regime ($V_{DS} \geq 3/\text{ALPHA}$):

$$I_d = (1 + \text{LAMBDA} \cdot V_{DS}) \frac{\text{BETA} \cdot V_{GT}^2}{1 + \text{B} \cdot V_{GT}}$$

VTO = $V_{bi} - V_{po}$ (Threshold voltage)

ALPHA = g_{ch} / I_{sat} (Saturation parameter)

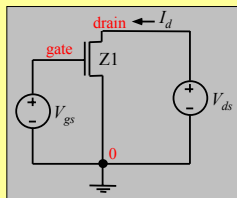
BETA : (Transconductance parameter)

LAMBDA : (Channel length modulation parameter)

B : (Doping tail extension parameter)

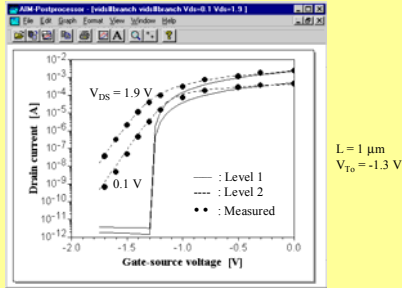
T. A. Fjeldly, T. Ytterdal, M. S. Shur, *Introduction to Device Modeling and Circuit Simulation*, Wiley, New York, 1998

Example: MESFET Subthreshold Characteristics



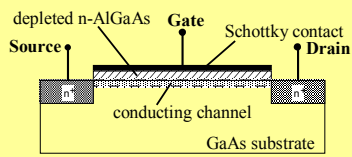
T. A. Fjeldly, T. Ytterdal, M. S. Shur, *Introduction to Device Modeling and Circuit Simulation*, Wiley, New York, 1998

MESFET Subthreshold Characteristics



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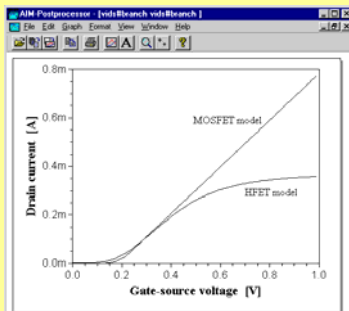
Basic HFET Model



Can use a MOSFET model as a first approximation because of the similarities between HFET and MOSFET.

T. A. Fjeldly, T. Ytterdal, M. S. Shur, *Introduction to Device Modeling and Circuit Simulation*, Wiley, New York, 1998

HFET Transfer Characteristics



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